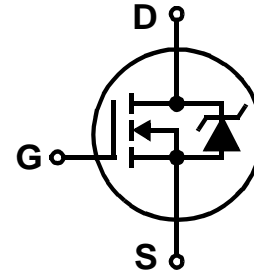


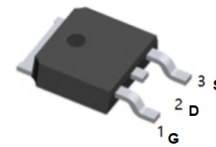
### Description

The D-PAK is designed for surface mounting using vapor phase, infrared, or wave soldering techniques. Power dissipation levels up to 1.5 watts are possible in typical surface mount applications.



### Features

- $V_{DS}$  (V) = 55V
- $I_D$  = 17A ( $V_{GS}$  = 10V)
- $R_{DS(ON)}$  = 75m $\Omega$  ( $V_{GS}$  = 10V)



TO-252(DPAK) top view

### Absolute Maximum Ratings

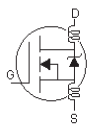
|                                   | Parameter                                | Max.         | Units |
|-----------------------------------|--|--------------|-------|
| $I_D$ @ $T_C = 25^\circ\text{C}$  | Continuous Drain Current, $V_{GS}$ @ 10V | 17           | A     |
| $I_D$ @ $T_C = 100^\circ\text{C}$ | Continuous Drain Current, $V_{GS}$ @ 10V | 12           |       |
| $I_{DM}$                          | Pulsed Drain Current ①⑥                  | 68           |       |
| $P_D$ @ $T_C = 25^\circ\text{C}$  | Power Dissipation                        | 45           | W     |
|                                   | Linear Derating Factor                   | 0.30         | W/°C  |
| $V_{GS}$                          | Gate-to-Source Voltage                   | $\pm 20$     | V     |
| $E_{AS}$                          | Single Pulse Avalanche Energy②⑥          | 71           | mJ    |
| $I_{AR}$                          | Avalanche Current①                       | 10           | A     |
| $E_{AR}$                          | Repetitive Avalanche Energy①             | 4.5          | mJ    |
| $dv/dt$                           | Peak Diode Recovery $dv/dt$ ③⑥           | 5.0          | V/ns  |
| $T_J$                             | Operating Junction and                   | -55 to + 175 | °C    |
| $T_{STG}$                         | Storage Temperature Range                |              |       |
|                                   | Soldering Temperature, for 10 seconds    |              |       |

### Thermal Resistance

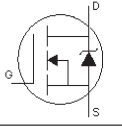
|                 | Parameter                     | Typ. | Max. | Units |
|-----------------|-------------------------------|------|------|-------|
| $R_{\theta JC}$ | Junction-to-Case              | ---  | 3.3  | °C/W  |
| $R_{\theta JA}$ | Case-to-Ambient (PCB mount)** | ---  | 50   |       |
| $R_{\theta JA}$ | Junction-to-Ambient           | ---  | 110  |       |

\*\* When mounted on 1" square PCB (FR-4 or G-10 Material) .  
For recommended footprint and soldering techniques refer to application note #AN-994

**Electrical Characteristics @ T<sub>J</sub> = 25°C (unless otherwise specified)**

|  | Parameter                            | Min. | Typ.  | Max.  | Units | Conditions  |
|--|--------------------------------------|------|-------|-------|-------|---|
| V <sub>(BR)DSS</sub>                   | Drain-to-Source Breakdown Voltage    | 55   | —     | —     | V     | V <sub>GS</sub> = 0V, I <sub>D</sub> = 250μA  |
| ΔV <sub>(BR)DSS</sub> /ΔT <sub>J</sub> | Breakdown Voltage Temp. Coefficient  | —    | 0.052 | —     | V/°C  | Reference to 25°C, I <sub>D</sub> = 1mA   |
| R <sub>DS(on)</sub>                    | Static Drain-to-Source On-Resistance | —    | —     | 0.075 | Ω     | V <sub>GS</sub> = 10V, I <sub>D</sub> = 10A ④                                       |
| V <sub>GS(th)</sub>                    | Gate Threshold Voltage               | 2.0  | —     | 4.0   | V     | V <sub>DS</sub> = V <sub>GS</sub> , I <sub>D</sub> = 250μA                          |
| g <sub>fs</sub>                        | Forward Transconductance             | 4.5  | —     | —     | S     | V <sub>DS</sub> = 25V, I <sub>D</sub> = 10A⑥  |
| I <sub>DSS</sub>                       | Drain-to-Source Leakage Current      | —    | —     | 25    | μA    | V <sub>DS</sub> = 55V, V <sub>GS</sub> = 0V   |
|  |                                      | —    | —     | 250   |       | V <sub>DS</sub> = 44V, V <sub>GS</sub> = 0V, T <sub>J</sub> = 150°C                 |
| I <sub>GSS</sub>                       | Gate-to-Source Forward Leakage       | —    | —     | 100   | nA    | V <sub>GS</sub> = 20V   |
|  | Gate-to-Source Reverse Leakage       | —    | —     | -100  |       | V <sub>GS</sub> = -20V  |
| Q <sub>g</sub>                         | Total Gate Charge                    | —    | —     | 20    | nC    | I <sub>D</sub> = 10A  |
| Q <sub>gs</sub>                        | Gate-to-Source Charge                | —    | —     | 5.3   |       | V <sub>DS</sub> = 44V   |
| Q <sub>gd</sub>                        | Gate-to-Drain ("Miller") Charge      | —    | —     | 7.6   |       | V <sub>GS</sub> = 10V, See Fig. 6 and 13 ④⑥   |
| t <sub>d(on)</sub>                     | Turn-On Delay Time                   | —    | 4.9   | —     | ns    | V <sub>DD</sub> = 28V   |
| t <sub>r</sub>                         | Rise Time                            | —    | 34    | —     |       | I <sub>D</sub> = 10A  |
| t <sub>d(off)</sub>                    | Turn-Off Delay Time                  | —    | 19    | —     |       | R <sub>G</sub> = 24Ω  |
| t <sub>f</sub>                         | Fall Time                            | —    | 27    | —     |       | R <sub>D</sub> = 2.6Ω, See Fig. 10 ④  |
| L <sub>D</sub>                         | Internal Drain Inductance            | —    | 4.5   | —     | nH    | Between lead,<br>6mm (0.25in.)<br>from package<br>and center of die contact⑤        |
| L <sub>S</sub>                         | Internal Source Inductance           | —    | 7.5   | —     |       |  |
| C <sub>iss</sub>                       | Input Capacitance                    | —    | 370   | —     | pF    | V <sub>GS</sub> = 0V  |
| C <sub>oss</sub>                       | Output Capacitance                   | —    | 140   | —     |       | V <sub>DS</sub> = 25V   |
| C <sub>rss</sub>                       | Reverse Transfer Capacitance         | —    | 65    | —     |       | f = 1.0MHz, See Fig. 5  |

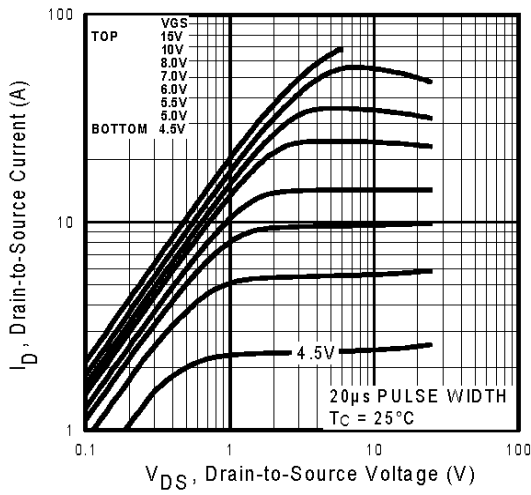
**Source-Drain Ratings and Characteristics**

|                 | Parameter                                 | Min.   | Typ. | Max. | Units | Conditions   |
|-----------------|---|--|------|------|-------|--|
| I <sub>S</sub>  | Continuous Source Current<br>(Body Diode) | —  | —    | 17 ⑤ | A     | MOSFET symbol<br>showing the<br>integral reverse<br>p-n junction diode.<br> |
| I <sub>SM</sub> | Pulsed Source Current<br>(Body Diode) ①   | —  | —    | 68   |       |  |
| V <sub>SD</sub> | Diode Forward Voltage                     | —  | —    | 1.3  | V     | T <sub>J</sub> = 25°C, I <sub>S</sub> = 10A, V <sub>GS</sub> = 0V ④  |
| t <sub>rr</sub> | Reverse Recovery Time                     | —  | 56   | 83   | ns    | T <sub>J</sub> = 25°C, I <sub>F</sub> = 10A  |
| Q <sub>rr</sub> | Reverse Recovery Charge                   | —  | 120  | 180  | nC    | di/dt = 100A/μs ④⑥   |
| t <sub>on</sub> | Forward Turn-On Time                      | Intrinsic turn-on time is negligible (turn-on is dominated by L <sub>S</sub> +L <sub>D</sub> ) |      |      |       |  |

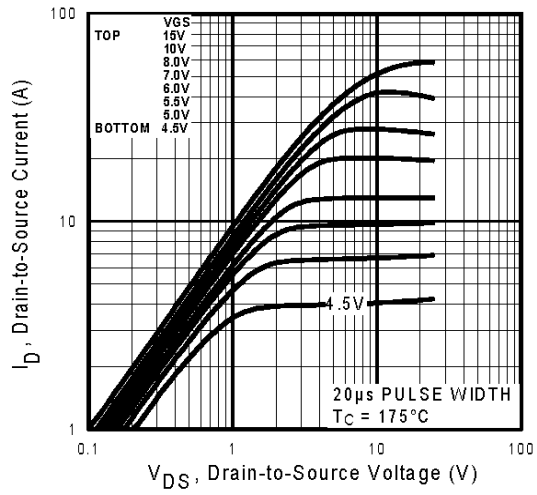
**Notes:**

- ① Repetitive rating; pulse width limited by max. junction temperature. ( See fig. 11 )
- ② V<sub>DD</sub> = 25V, starting T<sub>J</sub> = 25°C, L = 1.0mH  
R<sub>G</sub> = 25Ω, I<sub>AS</sub> = 10A. (See Figure 12)
- ③ I<sub>SD</sub> ≤ 10A, di/dt ≤ 280A/μs, V<sub>DD</sub> ≤ V<sub>(BR)DSS</sub>,  
T<sub>J</sub> ≤ 175°C

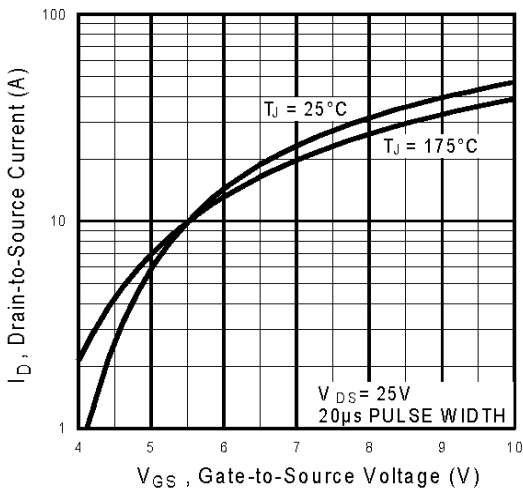
- ④ Pulse width ≤ 300μs; duty cycle ≤ 2%.
- ⑤ This is applied for I-PAK, L<sub>S</sub> of D-PAK is measured between lead and center of die contact.
- ⑥ Uses IRFZ24N data and test conditions.



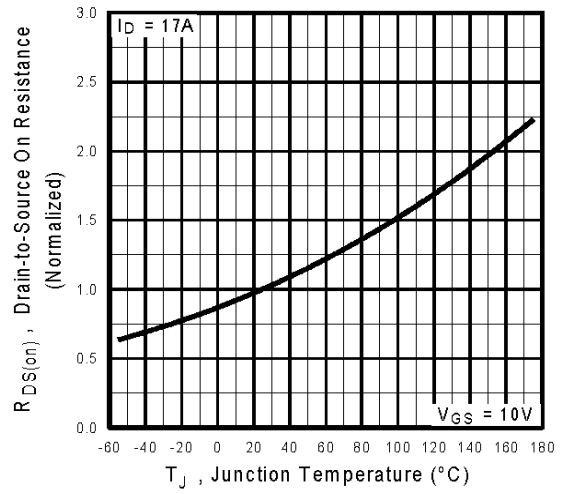
**Fig 1.** Typical Output Characteristics



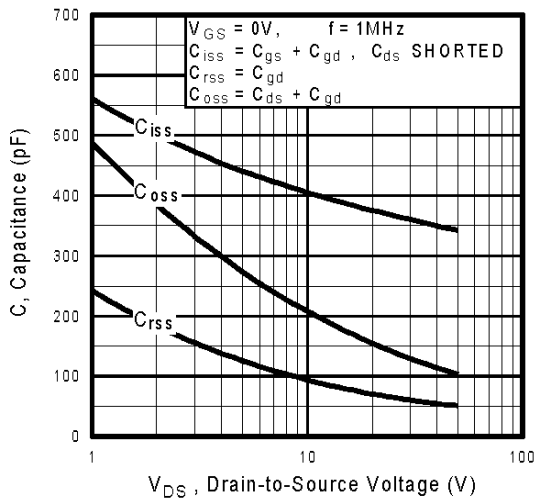
**Fig 2.** Typical Output Characteristics



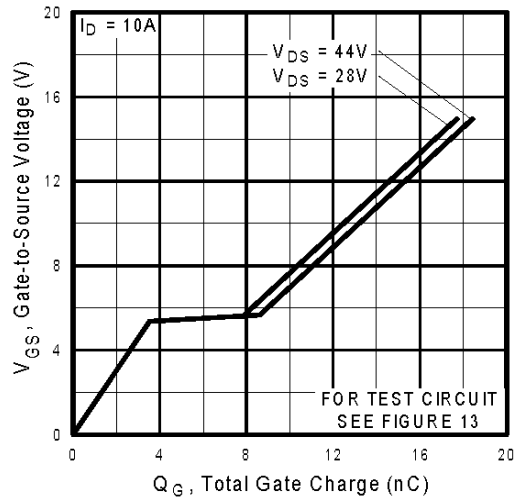
**Fig 3.** Typical Transfer Characteristics



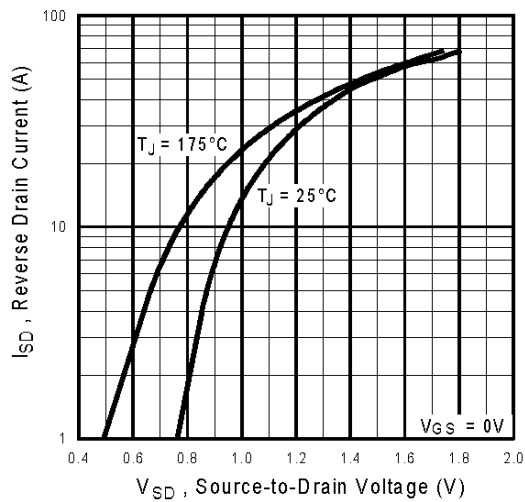
**Fig 4.** Normalized On-Resistance Vs. Temperature



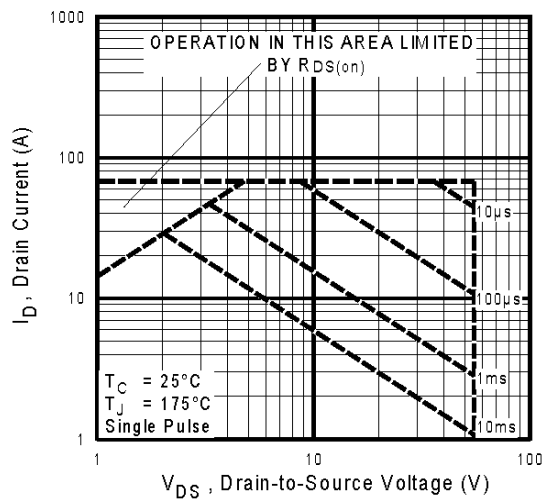
**Fig 5.** Typical Capacitance Vs. Drain-to-Source Voltage



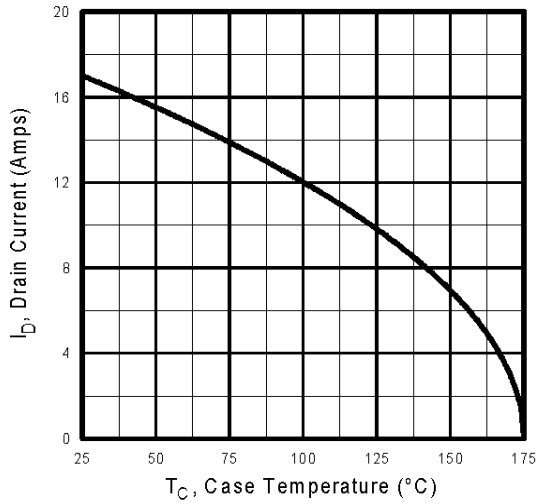
**Fig 6.** Typical Gate Charge Vs. Gate-to-Source Voltage



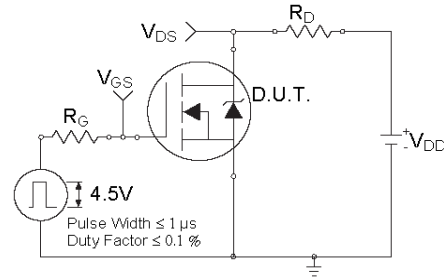
**Fig 7.** Typical Source-Drain Diode Forward Voltage



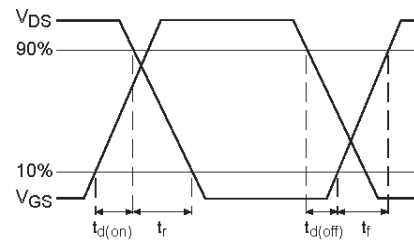
**Fig 8.** Maximum Safe Operating Area



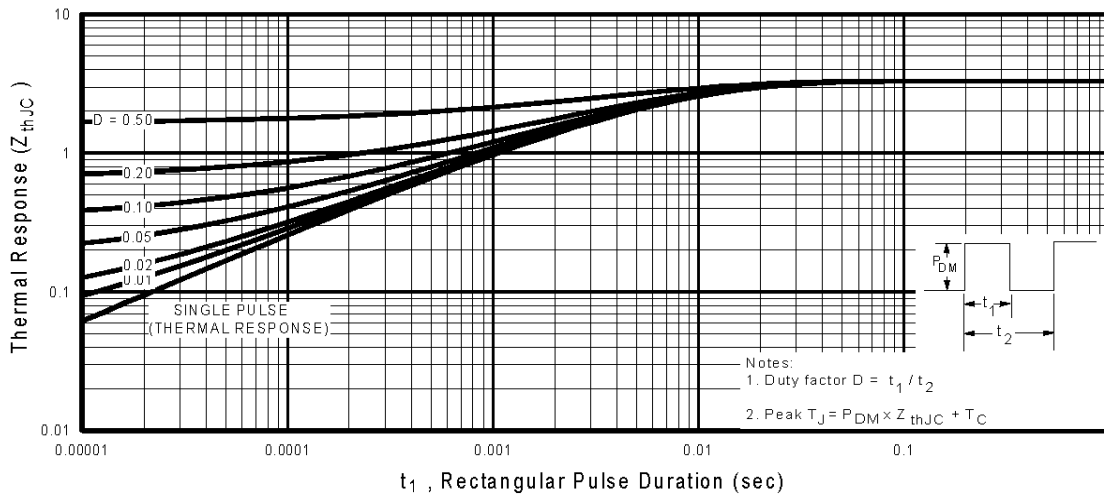
**Fig 9.** Maximum Drain Current Vs. Case Temperature



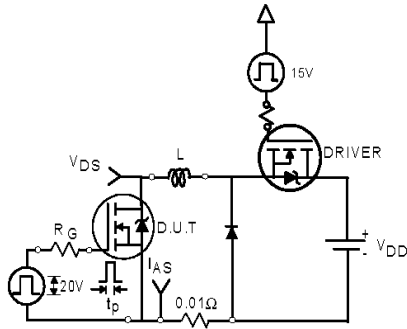
**Fig 10a.** Switching Time Test Circuit



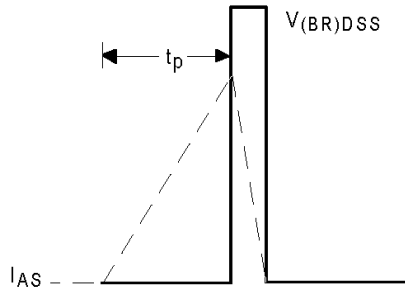
**Fig 10b.** Switching Time Waveforms



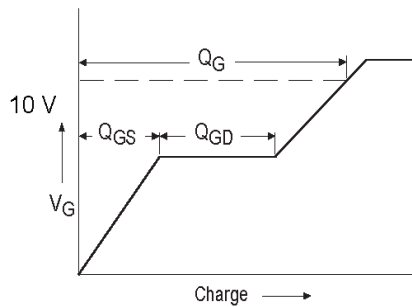
**Fig 11.** Maximum Effective Transient Thermal Impedance, Junction-to-Case



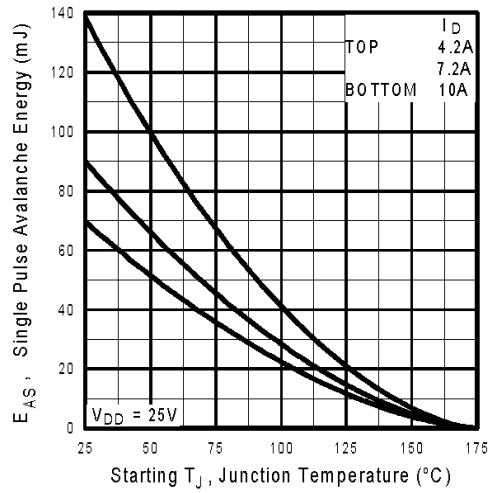
**Fig 12a.** Unclamped Inductive Test Circuit



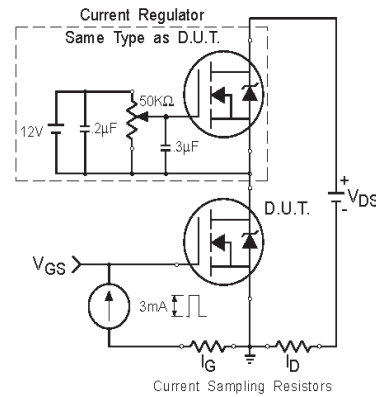
**Fig 12b.** Unclamped Inductive Waveforms



**Fig 13a.** Basic Gate Charge Waveform

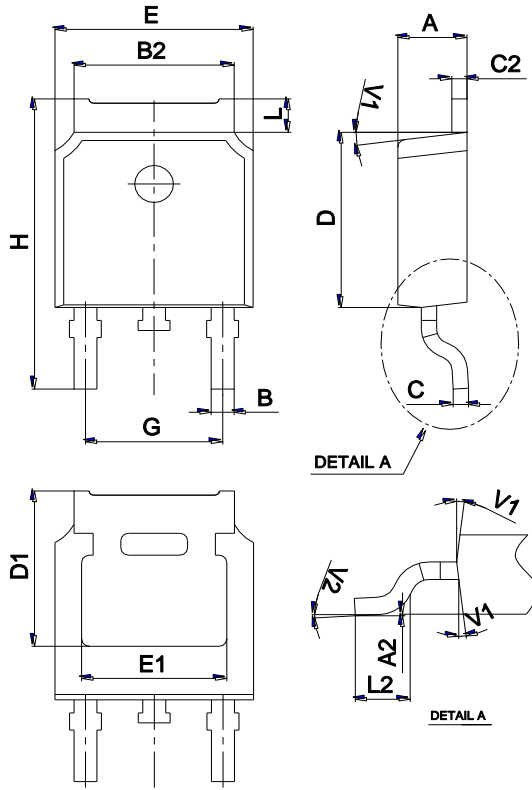


**Fig 12c.** Maximum Avalanche Energy Vs. Drain Current



**Fig 13b.** Gate Charge Test Circuit

Package Mechanical Data TO-252



| Ref. | Dimensions  |      |       |          |      |       |
|------|-------------|------|-------|----------|------|-------|
|      | Millimeters |      |       | Inches   |      |       |
|      | Min.        | Typ. | Max.  | Min.     | Typ. | Max.  |
| A    | 2.10        |      | 2.50  | 0.083    |      | 0.098 |
| A2   | 0           |      | 0.10  | 0        |      | 0.004 |
| B    | 0.66        |      | 0.86  | 0.026    |      | 0.034 |
| B2   | 5.18        |      | 5.48  | 0.202    |      | 0.216 |
| C    | 0.40        |      | 0.60  | 0.016    |      | 0.024 |
| C2   | 0.44        |      | 0.58  | 0.017    |      | 0.023 |
| D    | 5.90        |      | 6.30  | 0.232    |      | 0.248 |
| D1   | 5.30REF     |      |       | 0.209REF |      |       |
| E    | 6.40        |      | 6.80  | 0.252    |      | 0.268 |
| E1   | 4.63        |      |       | 0.182    |      |       |
| G    | 4.47        |      | 4.67  | 0.176    |      | 0.184 |
| H    | 9.50        |      | 10.70 | 0.374    |      | 0.421 |
| L    | 1.09        |      | 1.21  | 0.043    |      | 0.048 |
| L2   | 1.35        |      | 1.65  | 0.053    |      | 0.065 |
| V1   |             | 7°   |       |          | 7°   |       |
| V2   | 0°          |      | 6°    | 0°       |      | 6°    |

Ordering information

| Order code     | Package | Baseqty | Delivery mode |
|----------------|---------|---------|---------------|
| UMW IRFR024NTR | TO-252  | 2500    | Tape and reel |

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